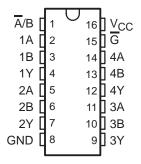
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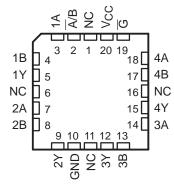
- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current Outputs Drive Up To 15 LSTTL Loads
- Typical t_{pd} = 15 ns
- Low Power Consumption, 80-μA Max I_{CC}

SN54HCT157 ... J OR W PACKAGE SN74HCT157 ... D OR N PACKAGE (TOP VIEW)



- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- Buffered Inputs and Outputs

SN54HCT157 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These data selectors/multiplexers contain inverters and drivers to supply full data selection to the four output gates. A separate strobe (\overline{G}) input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs.

ORDERING INFORMATION

TA	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HCT157N	SN74HCT157N
4000 1- 0500		Tube of 40	SN74HCT157D	
-40°C to 85°C	SOIC - D	Reel of 2500	SN74HCT157DR	HCT157
		Reel of 250	SN74HCT157DT	
	CDIP – J	Tube of 25	SNJ54HCT157J	SNJ54HCT157J
−55°C to 125°C	CFP – W	Tube of 150	SNJ54HCT157W	SNJ54HCT157W
	LCCC - FK	Tube of 55	SNJ54HCT157FK	SNJ54HCT157FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

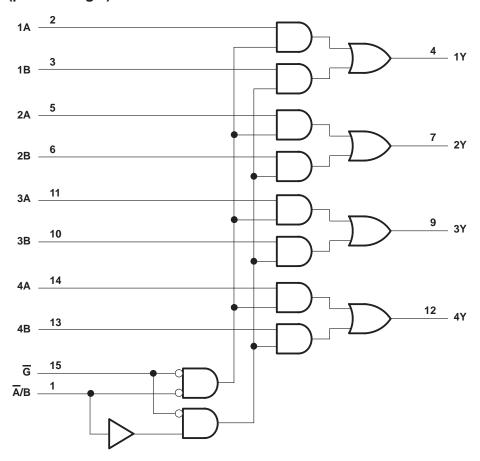


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FUNCTION TABLE

	INPUTS										
STROBE	SELECT	DA	TA	OUTPUT							
G	A/B	Α	В	·							
Н	Х	Х	Х	L							
L	L	L	X	L							
L	L	Н	X	Н							
L	Н	Χ	L	L							
L	Н	X	Н	Н							

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	
N package	
Storage temperature range, T _{Stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	54HCT1	57	SN	74HCT1	57	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	\$ 5.5	4.5	5	5.5	V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2	Į.	1/5	2			V
V _{IL}	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V		77	0.8			0.8	V
VI	Input voltage		0	1	VCC	0		VCC	V
VO	Output voltage		0	2	VCC	0		VCC	V
t _t	Input transition (rise and fall) time		0~	5	500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555		.,	Т	A = 25°C	;	SN54H	CT157	SN74H	CT157	UNIT	
PARAMETER	TEST CON	IDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
V	Mr. Mr. and	I _{OH} = -20 μA	45.77	4.4	4.499		4.4		4.4		.,
Voн	VI = VIH or VIL	I _{OH} = -6 mA	4.5 V	3.98	4.3		3.7	3	3.84		V
.,	V VV	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	٧
V _{OL}	$V_I = V_{IH}$ or V_{IL}	I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	V
lį	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100	1	±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V			8	2	160		80	μΑ
ΔICC [†]	One input at 0.5 V o Other inputs at 0 or	,	5.5 V		1.4	2.4	704d	3		2.9	mA
Ci		4.5 V to 5.5 V		3	10		10*		10	pF	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	.,	T	λ = 25°C	;	SN54HCT15	7 SI	N74HCT157	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN MA	ΧI	MIN MAX	UNIT
	A == D	V	4.5 V		18	28	4	2	3	5
	A or B	Y	5.5 V		15	25	3	8	32	2
	Ā/B	V	4.5 V		20	32	0-4	8	40	
^t pd	A/B	Y	5.5 V		17	29	2 4	3	36	ns
	G	Υ	4.5 V		18	26	50 3	9	33	3
			5.5 V		15	23	3	5	30)
4.		Any	4.5 V		8	15	2 2	2	19	
t _t		Any	5.5 V		7	14	2	1	17	ns ns

switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

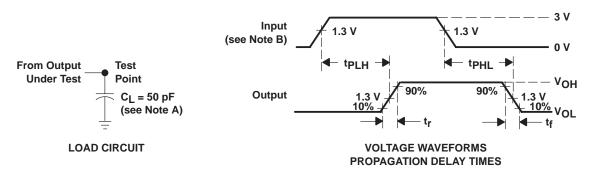
DADAMETER	FROM	то		T,	ղ = 25°C	;	SN54H	CT157	SN74H	CT157	UNIT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
	A - :: D	Y	4.5 V		23	42		63		52	
	A or B	Y	5.5 V		19	38		52		46	
	Ā/B G	V	4.5 V		24	46		4/72		58	
^t pd		Y	5.5 V		21	41	1	61		52	ns
		Y	4.5 V		21	39	2	58		48	
			5.5 V		19	35	20,	49		43	
4.		Any	4.5 V		17	42	y d	63		53	20
t _t		Any	5.5 V		14	38		57		48	ns

operating characteristics, T_A = 25°C

		PARAMETER	TEST CONDITIONS	TYP	UNIT
ľ	C _{pd}	Power dissipation capacitance	No load	12	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_\Gamma = 6$ ns, $t_f = 6$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpl H and tpHI are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74HCT157D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157DTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT157N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HCT157NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

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to Customer on an annual basis.	



TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT157DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



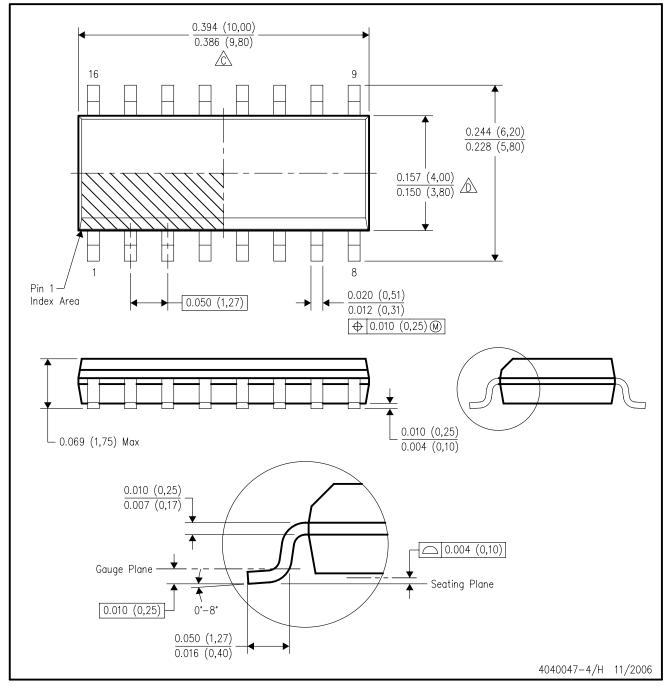


*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74HCT157DR	SOIC	D	16	2500	333.2	345.9	28.6

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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